

Effect of Composition on Thermoelectric Properties of Polycrystalline CrSi₂

S. PERUMAL,¹ S. GORSSE,^{2,3} U. AIL,² R. DECOURT,²
and A.M. UMARJI¹

1.—Materials Research Centre, Indian Institute of Science, Bangalore 560012, India. 2.—Univ. Bordeaux, ICMCB, CNRS, F-33608 Pessac, France. 3.—e-mail: gorsse@icmcb-bordeaux.cnrs.fr

Ingots with compositions CrSi_{2-x} (with 0 < x < 0.1) were synthesized by vacuum arc melting followed by uniaxial hot pressing for densification. This paper reports the temperature and composition dependence of the electrical resistivity, Seebeck coefficient, and thermal conductivity of CrSi_{2-x} samples in the temperature range of 300 K to 800 K. The silicon-deficient samples exhibited substantial reductions in resistivity and Seebeck coefficient over the measured temperature range due to the formation of metallic secondary CrSi phase embedded in the CrSi₂ matrix phase. The thermal conductivity was seen to exhibit a U-shaped curve with respect to x, exhibiting a minimum value at the composition of x = 0.04. However, the limit of the homogeneity range of CrSi₂ suppresses any further decrease of the lattice thermal conductivity. As a consequence, the maximum figure of merit of ZT = 0.1 is obtained at 650 K for CrSi_{1.98}.

Key words: Thermoelectric materials, chromium disilicide, intermetallics

INTRODUCTION

Transition-metal (TM) silicides have attracted attention for high-temperature thermoelectric applications and Si-based microelectronics due to their thermal and structural stability, high electrical conductivity and thermoelectric power at elevated temperature, and the natural abundance of their constituent elements.^{1,2} The usefulness of thermoelectric materials can be determined by a dimensionless performance index called the figure of merit $ZT = S^2T/\kappa\rho$, where S, ρ, κ, and T are the Seebeck coefficient, electrical resistivity, thermal conductivity, and absolute temperature, respectively.

Chromium disilicide (CrSi₂) is regarded as a potential p-type thermoelectric (TE) material for high-temperature applications because it exhibits very high-temperature oxidation resistance up to 1000°C and $ZT = 0.25$ parallel to the c-axis, whereas $ZT = 0.07$ in the direction perpendicular to the c-axis,² which is limited by a slightly high

thermal conductivity (10 W/mK).³ CrSi₂ is a degenerate,⁴⁻⁶ indirect-band-gap^{7,8} (0.35 eV) semiconducting material. It has a hexagonal crystal structure (lattice parameters $a = 4.4281$ Å, $c = 6.3691$ Å) with space group $P6_322$, and band-structure calculations also confirm that CrSi₂ is a narrow-gap semiconductor with band gap of 0.30 eV, showing good agreement with experimental values reported in the literature.⁹⁻¹¹

According to the Cr-Si phase diagram,¹² CrSi₂ exhibits a narrow homogeneity range. Change in the composition of CrSi₂ should lead to corresponding variation in S, ρ, and κ due to change in the carrier concentration (n) and energy band gap (E_g) and by the created defects. Furthermore, as the percentage Si concentration in CrSi₂ either increases or decreases beyond the solubility range, formation of secondary phases of Si or metallic CrSi will result, respectively. The secondary metallic CrSi phase has thermal conductivity of ~12 W/m K, which is slightly higher than that of pure semiconducting CrSi₂.¹³ In this work, an attempt was made to search for the optimum composition in the range